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FOREWORD

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Plasma Processing

This special issue contains original and review papers based on the presentations at the 9th International Conference on Reactive Plasmas (ICRP-9)/68th Gaseous Electronics Conference (GEC-68)/33rd Symposium on Plasma Processing (SPP-33), held in Hawaii Convention Center, Honolulu, U.S.A., on October 12–16, 2015 under the sponsorship of the Japan Society of Applied Physics (JSAP) and American Physical Society (APS). SPP is an annual domestic meeting organized by the Division of Plasma Electronics, JSAP, and generally every three years the meeting is held as an international conference ICRP. Joint conference of ICRP has been held in Maui (ICRP-4, 1998, jointly organized with GEC), in Grenoble (ICRP-5, 2002, jointly organized with ESCAMPIG), in Paris (ICRP-7, 2010, jointly organized with GEC), and this is the fourth joint conferences of ICRP. The scope of the conference covers all areas of plasma electronics, with emphasis on the basic aspects of reactive plasmas and their applications. The conference had 605 participants from 37 countries and 656 papers were presented. The 37 papers included in this special issue are peer-reviewed selections from optional paper submissions to the special issue. The papers in this issue are classified into 7 categories, which are partly different from the session classification in the conference. The range of application of reactive plasma has been steadily widening. Plasmas interacting with liquids are now one of the important research areas in this field. New applications of plasmas in environmental technology, life science, and agriculture are under active investigations. Precise control of plasma properties has become even more important in plasma processing in electronics and nanotechnology. For all these fields and other emerging applications, basic understanding of underlying physics and chemistry is definitely important. We hope that the present special issue serves as a rich source of knowledge for promoting low-temperature plasma science and technology.

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